



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR D<sup>2</sup>PAK (TO-263), TO-220</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	2880	1 420 000	200 °C + N2	0	0.00
HAST	13 858	1 385 800	130 °C, 85 % RH	0	0.00
Power Cycle	11 890	95 943 198	DELTA T <sub>J</sub> = 100 °C	0	0.00
Pressure Pot	12 628	1 212 288	121°, 15 PSIG	0	0.00
Solder DUNK	7410	88 560	260 °C, 10 s	0	0.00
Solderability	2095	16 605	883 M2003	0	0.00
Temp. Cycle	11 707	10 972 000	-55 °C to 150 °C	0	0.00